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Direct writing imaging exposure equipment

直写成像式曝光设备

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Foreword

This document is in accordance with the provisions of GB/T 1.1-2020 "Guidelines for standardization work Part 1: Structure and drafting rules for standardization documents" Drafting.

Please note that some of the contents of this document may involve patents. The issuing organization of this document does not assume the responsibility for identifying patents.

This document was proposed and coordinated by the National Technical Committee for Semiconductor Equipment and Materials Standardization (SAC/TC203).

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Direct writing imaging exposure equipment

1 Scope

This document specifies the classification and structure, technical requirements, inspection rules, marking, packaging, transportation and storage of direct writing imaging exposure equipment and The requirements for the product random documents describe the test methods, including general test conditions, appearance and dimensional inspection, performance tests, safety tests and Noise test.

This document applies to the design, development, verification, manufacture, use and maintenance of direct-write imaging exposure equipment for printed circuit boards and integrated circuit packaging substrates. Use and inspection processes.

2 Normative references

GB/T 191

GB/T 2893.2

GB/T 3768

GB/T 3785.1

GB/T 5226.1-2019

GB/T 6388

GB/T 13306

GB/T 13384

GB/T 16471

GB/T 18209.2-2010

3 Terms and definitions

The terms and definitions defined in SJ/T 10668-2023 and the following apply to this document.

3.1

A device that uses light reflection, electro-optical interaction, acousto-optical interaction, etc. to change the direction of light propagation or energy distribution.

3.2

A technology that uses a laser diode, light-emitting diode or other light source to scan a beam through a spatial light modulator (3.1).

3.3 Resolution

In optical exposure imaging, the minimum graphic size that can produce a clear image by an exposure device or a photosensitive material such as a photoresist.

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